

IN THE CLAIMS:

Claims 1-31 have been amended herein. All of the pending claims 1 through 31 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) A combination of a semiconductor substrate singulation saw and a chuck for holding a substrate comprising:  
a saw having at least one blade supported above a table and oriented to cut mutually parallel paths in ~~the~~ a surface of a semiconductor substrate positioned on ~~said the~~ the table; and  
a chuck having at least one cutting pedestal located thereon mounted on ~~said the~~ the table, ~~said the~~ the chuck for holding ~~said the~~ the substrate during cutting thereof by ~~said the~~ the saw.
2. (Currently Amended) The combination of claim 1, wherein ~~said the~~ the chuck further comprises:  
a chuck table; and  
a plurality of cutting pedestals, each cutting pedestal being mounted on ~~said the~~ the chuck table.
3. (Currently Amended) The combination of claim 2, wherein ~~said the~~ the chuck further comprises:  
at least one clamp pedestal; and  
at least one substrate clamp removably attached to a portion of the at least one clamp pedestal.
4. (Currently Amended) The combination of claim 3, wherein ~~said the~~ the chuck further comprises:  
at least one alignment apparatus having a portion attached to the chuck table.

5. (Currently Amended) The combination of claim 4, wherein ~~said~~ the at least one alignment apparatus comprises:

at least one alignment pin having a portion for engaging a portion of the substrate.

6. (Currently Amended) The combination of claim 4, wherein ~~said~~ the at least one alignment apparatus comprises:

an aperture in the chuck table for receiving ~~said~~ the substrate therein.

7. (Currently Amended) The combination of claim 4, wherein ~~said~~ the at least one alignment apparatus comprises:

a pair of alignment pins, each alignment pin having a portion thereof attached to the chuck table and a portion thereof for engaging a portion of ~~said~~ the substrate.

8. (Currently Amended) The combination of claim 1, wherein the saw further ~~comprising~~ comprises:

at least two blades for sawing ~~said~~ the substrate.

9. (Currently Amended) The combination of claim 8, wherein at least one of ~~said~~ the at least two blades is laterally translatable relative to another of ~~said~~ the at least two blades.

10. (Currently Amended) The combination of claim 9, wherein ~~said~~ the at least one of ~~said~~ the at least two blades is raisable relative ~~to~~ to the another of ~~said~~ the at least two blades.

11. (Currently Amended) The combination of claim 8, wherein ~~said~~ the table is translatable in at least one direction relative to ~~said~~ the at least two blades.

12. (Currently Amended) The combination of claim 8, wherein ~~said~~ the at least two blades are translatable in at least one direction relative to ~~said~~ the table.

13. (Currently Amended) A combination of a semiconductor substrate singulation saw and a table for mounting a substrate comprising:  
a saw having at least two blades supported above a table and oriented to cut mutually parallel paths in a surface of a semiconductor substrate positioned on-~~said~~ the table; and  
a chuck having at least one cutting pedestal located thereon mounted on-~~said~~ the table, -~~said~~ the chuck for holding-~~said~~ the substrate during cutting thereof by-~~said~~ the saw.

14. (Currently Amended) The combination of claim 13, wherein-~~said~~ the chuck further comprises:  
a chuck table; and  
a plurality of cutting pedestals, each cutting pedestal being mounted on-~~said~~ the chuck table.

15. (Currently Amended) The combination of claim 14, wherein-~~said~~ the chuck further comprises:  
at least one clamp pedestal; and  
at least one substrate clamp removably attached to a portion of the at least one clamp pedestal.

16. (Currently Amended) The combination of claim 15, wherein-~~said~~ the chuck further comprises:  
at least one alignment apparatus having a portion thereof attached to the chuck table.

17. (Currently Amended) The combination of claim 16, wherein-~~said~~ the at least one alignment apparatus comprises:  
at least one alignment pin having a portion for engaging a portion of the substrate.

18. (Currently Amended) The combination of claim 16, wherein-~~said~~ the at least one alignment apparatus comprises:  
an aperture in the chuck table for receiving-~~said~~ the substrate therein.

19. (Currently Amended) The combination of claim 16, wherein ~~said~~ the at least one alignment apparatus comprises:

a pair of alignment pins, each alignment pin having a portion thereof attached to the chuck table and a portion thereof for engaging a portion of ~~said~~ the substrate.

20. (Currently Amended) The combination of claim 13, wherein the saw further ~~comprising~~ comprises:  
at least two blades for sawing ~~said~~ the substrate.

21. (Currently Amended) The combination of claim 20, wherein at least one of ~~said~~ the at least two blades is laterally translatable relative to another of ~~said~~ the at least two blades.

22. (Currently Amended) The combination of claim 21, wherein ~~said~~ the at least one of ~~said~~ the at least two blades is raisable relative to ~~to the~~ another of ~~said~~ the at least two blades.

23. (Currently Amended) The combination of claim 20, wherein ~~said~~ the table is translatable in at least one direction relative to ~~said~~ the at least two blades.

24. (Currently Amended) The combination of claim 20, wherein ~~said~~ the at least two blades are translatable in at least one direction relative to ~~said~~ the table.

25. (Currently Amended) A chuck used ~~for~~ in semiconductor substrate singulation for holding a substrate to be singulated ~~in~~ by a saw having a table comprising:  
a chuck having at least one cutting pedestal located thereon mounted on ~~said~~ the table, ~~said~~ the chuck for holding ~~said~~ the substrate during cutting thereof by ~~said~~ the saw.

26. (Currently Amended) The chuck of claim 25, ~~wherein said chuck~~ further ~~comprises~~ comprising:  
a plurality of cutting pedestals, each cutting pedestal being mounted on ~~said~~ the table.

27. (Currently Amended) The chuck of claim 26, ~~wherein said chuck~~ further ~~comprises~~ comprising:  
at least one clamp pedestal; and  
at least one substrate clamp removably attached to a portion of the at least one clamp pedestal.

28. (Currently Amended) The chuck of claim 27, ~~wherein said chuck~~ further ~~comprises~~ comprising:  
at least one alignment apparatus having a portion attached to the ~~chuck~~ table.

29. (Currently Amended) The chuck of claim 28, wherein ~~said~~ the at least one alignment apparatus comprises:  
at least one alignment pin having a portion for engaging a portion of the substrate.

30. (Currently Amended) The chuck of claim 28, wherein ~~said~~ the at least one alignment apparatus comprises:  
an aperture in the ~~chuck~~ table for receiving ~~said~~ the substrate therein.

31. (Currently Amended) The chuck of claim 28, wherein ~~said~~ the at least one alignment apparatus comprises:  
a pair of alignment pins, each alignment pin having a portion thereof attached to the ~~chuck~~ table  
and a portion thereof for engaging a portion of ~~said~~ the substrate.